



## Material Content Data Sheet



Sales Product Name	BG 3123 H6327				Issued		29. August 2013	
MA#	MA000845496							
Package	PG-SOT363-6-4				Weight*		6.27 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		12	
	noble metal	gold	7440-57-5	0.007	0.12		1166	
	inorganic material	silicon	7440-21-3	0.038	0.60	0.72	6048	7226
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		92	
	non noble metal	titanium	7440-32-6	0.003	0.05		458	
	non noble metal	chromium	7440-47-3	0.009	0.14		1374	
	non noble metal	copper	7440-50-8	2.860	45.61	45.81	456209	458133
wire	non noble metal	copper	7440-50-8	0.012	0.20	0.20	1969	1969
encapsulation	organic material	carbon black	1333-86-4	0.031	0.49		4891	
	plastics	epoxy resin	-	0.659	10.52		105159	
	inorganic material	silicondioxide	60676-86-0	2.376	37.91	48.92	379060	489110
leadfinish	non noble metal	tin	7440-31-5	0.213	3.40	3.40	34014	34014
plating	noble metal	silver	7440-22-4	0.060	0.95	0.95	9548	9548
*deviation	< 10%	Sum in total:			100,00			1000000

### Important Remarks:

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